

ABSTRACT

An object of the present invention is to provide a polishing pad that is prevented from causing an end-point
5 detection error due to a reduction in light transmittance
from the early stage to the final stage of the process, and
to provide a method of producing a semiconductor device
with the polishing pad. The present invention is directed
to a polishing pad, comprising a polishing layer comprising
10 a polishing region and a light-transmitting region, wherein
a polishing side surface of the light-transmitting region
is subjected to a surface roughness treatment, and the
light-transmitting region has a light transmittance of 40%
to 60% at a wavelength of 600 nm before use.